

REMARKS/ARGUMENTS

Claims 1 and 5-10 are pending, of which claims 1 and 5-7 have been withdrawn. Claims 3, 4, and 11 have been canceled without prejudice and without disclaimer. Claim 8 has been amended to include the limitation of previous claim 11 which is not canceled. No new matter has been introduced. Because dependent claim 11 was previously presented for examination, Applicants believe the amendment of claim 8 to include the limitations of dependent claim 11 does not raise any new issues or require additional searches.

Claims 8-10 stand rejected under 35 U.S.C. § 103(a) as being unpatentable over Ohashi et al. (US 6,507,464) in view of Chen et al. (US 6,776,891).

Applicants respectfully submit that claim 8 as amended is patentable over Ohashi et al. and Chen et al. because, for instance, they do not teach or suggest that the magnetic layer, which is nearest to the magnetic gap of the magnetic layers, contains Co, Ni, and Fe, with $20 \leq \text{Co} \leq 40 \text{ wt\%}$, $0 < \text{Ni} \leq 2 \text{ wt\%}$, and $60 \leq \text{Fe} \leq 80 \text{ wt\%}$, and has a saturation magnetic flux density of 23,000 gauss or more. This composition of the nearest magnetic layer is different from that of the nearest magnetic layer in Ohashi et al., which contains $50 \leq \text{Co} \leq 80 \text{ wt\%}$, $3 < \text{Ni} \leq 10 \text{ wt\%}$, and $20 \leq \text{Fe} \leq 40 \text{ wt\%}$, as disclosed at column 2, line 65 to column 3, line 2. These three ranges of Co, Ni, and Fe do not overlap at all. Chen et al. fails to cure the deficiencies of Ohashi et al.

The present invention provides a smooth, thick, glossy, and clear CoNiFe alloy film with a high corrosion resistance so that a saturation flux density of 23000 gauss or more (higher than that of Ohashi et al.) has been achieved. See paragraph [0010] at page 2, lines 15-17; and paragraph [0041] at page 8, lines 17-21.

For at least the foregoing reasons, claim 8 and claims 9-10 depending therefrom are patentable over Ohashi et al. and Chen et al. Upon allowance of claims 8-10, Applicants would cancel the withdrawn claims.

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PATENT

CONCLUSION

In view of the foregoing, Applicants believe all claims now pending in this Application are in condition for allowance and an action to that end is respectfully requested.

If the Examiner believes a telephone conference would expedite prosecution of this application, please telephone the undersigned at 650-326-2400.

Respectfully submitted,



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